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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	ARM® Cortex®-M3
Core Size	32-Bit Single-Core
Speed	48MHz
Connectivity	I²C, IrDA, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	47
Program Memory Size	256KB (256K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	24K x 8
Voltage - Supply (Vcc/Vdd)	1.62V ~ 3.6V
Data Converters	A/D 10x10b; D/A 1x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	64-LQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/atsam3n4ba-au

1.1 Configuration Summary

The SAM3N4/2/1/0/00 differ in memory size, package and features list. Table 1-1 summarizes the configurations of the 9 devices.

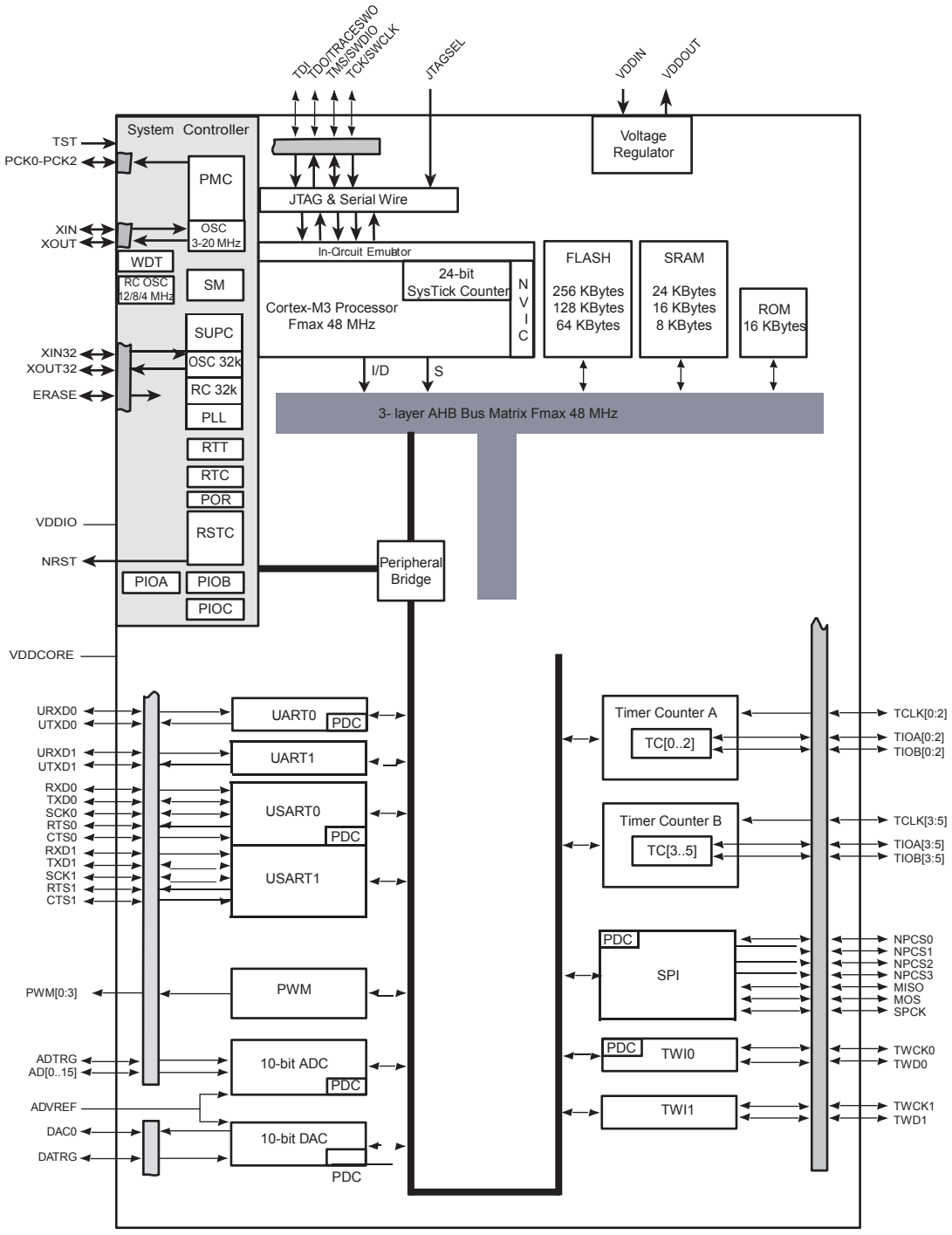
Table 1-1. Configuration Summary

Device	Flash	SRAM	Package	Number of PIOs	ADC	Timer	PDC Channels	USART	DAC
SAM3N4A	256 Kbytes	24 Kbytes	LQFP48 QFN48	34	8 channels	6(1)	8	1	_
SAM3N4B	256 Kbytes	24 Kbytes	LQFP64 QFN64	47	10 channels	6(2)	10	2	1
SAM3N4C	256 Kbytes	24 Kbytes	LQFP100 BGA100	79	16 channels	6	10	2	1
SAM3N2A	128 Kbytes	16 Kbytes	LQFP48 QFN48	34	8 channels	6(1)	8	1	_
SAM3N2B	128 Kbytes	16 Kbytes	LQFP64 QFN64	47	10 channels	6((2)	10	2	1
SAM3N2C	128 Kbytes	16 Kbytes	LQFP100 BGA100	79	16 channels	6	10	2	1
SAM3N1A	64 Kbytes	8 Kbytes	LQFP48 QFN48	34	8 channels	6(1)	8	1	_
SAM3N1B	64 Kbytes	8 Kbytes	LQFP64 QFN64	47	10 channels	6(2)	10	2	1
SAM3N1C	64 Kbytes	8 Kbytes	LQFP100 BGA100	79	16 channels	6	10	2	1
SAM3N0A	32 Kbytes	8 Kbytes	LQFP48 QFN48	34	8 channels	6(1)	8	1	_
SAM3N0B	32 Kbytes	8 Kbytes	LQFP64 QFN64	47	10 channels	6(2)	10	2	1
SAM3N0C	32 Kbytes	8 Kbytes	LQFP100 BGA100	79	16 channels	6	10	2	1
SAM3N00A	16 Kbytes	4 KBytes	LQFP48 QFN48	34	8 channels	6(1)	8	1	_
SAM3N00B	16 Kbytes	4 KBytes	LQFP64 QFN64	47	10 channels	6(2)	10	2	1

Notes: 1. Only two TC channels are accessible through the PIO.
2. Only three TC channels are accessible through the PIO.

2. SAM3N Block Diagram

Figure 2-1. SAM3N 100-pin version Block Diagram



3. Signal Description

Table 3-1 gives details on the signal name classified by peripheral.

Table 3-1. Signal Description List

Signal Name	Function	Type	Active Level	Voltage Reference	Comments
Power Supplies					
VDDIO	Peripherals I/O Lines Power Supply	Power			1.62V to 3.6V
VDDIN	Voltage Regulator, ADC and DAC Power Supply	Power			1.8V to 3.6V(3)
VDDOUT	Voltage Regulator Output	Power			1.8V Output
VDDPLL	Oscillator and PLL Power Supply	Power			1.65 V to 1.95V
VDDCORE	Power the core, the embedded memories and the peripherals	Power			1.65V to 1.95V Connected externally to VDDOUT
GND	Ground	Ground			
Clocks, Oscillators and PLLs					
XIN	Main Oscillator Input	Input		VDDIO	Reset State: - PIO Input - Internal Pull-up disabled - Schmitt Trigger enabled(1)
XOUT	Main Oscillator Output	Output			
XIN32	Slow Clock Oscillator Input	Input			
XOUT32	Slow Clock Oscillator Output	Output			
PCK0 - PCK2	Programmable Clock Output	Output			Reset State: - PIO Input - Internal Pull-up enabled - Schmitt Trigger enabled(1)
ICE and JTAG					
TCK/SWCLK	Test Clock/Serial Wire Clock	Input		VDDIO	Reset State: - SWJ-DP Mode - Internal pull-up disabled - Schmitt Trigger enabled(1)
TDI	Test Data In	Input			
TDO/TRACESWO	Test Data Out/Trace Asynchronous Data Out	Output			
TMS/SWDIO	Test Mode Select /Serial Wire Input/Output	Input / I/O			
JTAGSEL	JTAG Selection	Input	High		Permanent Internal pull-down

4.1.3 100-Lead LQFP Pinout

Table 4-1. 100-lead LQFP SAM3N4/2/1/0/00C Pinout

1	ADVREF	26	GND	51	TDI/PB4	76	TDO/TRACESWO/PB5
2	GND	27	VDDIO	52	PA6/PGMNOE	77	JTAGSEL
3	PB0/AD4	28	PA16/PGMD4	53	PA5/PGMRDY	78	PC18
4	PC29/AD13	29	PC7	54	PC28	79	TMS/SWDIO/PB6
5	PB1/AD5	30	PA15/PGMD3	55	PA4/PGMNCMD	80	PC19
6	PC30/AD14	31	PA14/PGMD2	56	VDDCORE	81	PA31
7	PB2/AD6	32	PC6	57	PA27	82	PC20
8	PC31/AD15	33	PA13/PGMD1	58	PC8	83	TCK/SWCLK/PB7
9	PB3/AD7	34	PA24	59	PA28	84	PC21
10	VDDIN	35	PC5	60	NRST	85	VDDCORE
11	VDDOUT	36	VDDCORE	61	TST	86	PC22
12	PA17/PGMD5/AD0	37	PC4	62	PC9	87	ERASE/PB12
13	PC26	38	PA25	63	PA29	88	PB10
14	PA18/PGMD6/AD1	39	PA26	64	PA30	89	PB11
15	PA21/AD8	40	PC3	65	PC10	90	PC23
16	VDDCORE	41	PA12/PGMD0	66	PA3	91	VDDIO
17	PC27	42	PA11/PGMM3	67	PA2/PGMEN2	92	PC24
18	PA19/PGMD7/AD2	43	PC2	68	PC11	93	PB13/DAC0
19	PC15/AD11	44	PA10/PGMM2	69	VDDIO	94	PC25
20	PA22/AD9	45	GND	70	GND	95	GND
21	PC13/AD10	46	PA9/PGMM1	71	PC14	96	PB8/XOUT
22	PA23	47	PC1	72	PA1/PGMEN1	97	PB9/*PGMCK/XIN*
23	PC12/AD12	48	PA8/XOUT32/ PGMM0	73	PC16	98	VDDIO
24	PA20/AD3	49	PA7/XIN32/ PGMNVALID	74	PA0/PGMEN0	99	PB14
25	PC0	50	VDDIO	75	PC17	100	VDDPLL

4.2 SAM3N4/2/1/0/00B Package and Pinout

Figure 4-3. Orientation of the 64-pad QFN Package

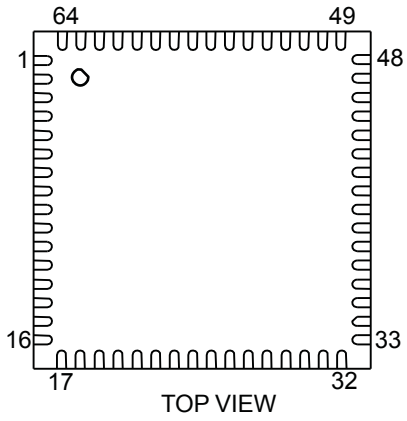
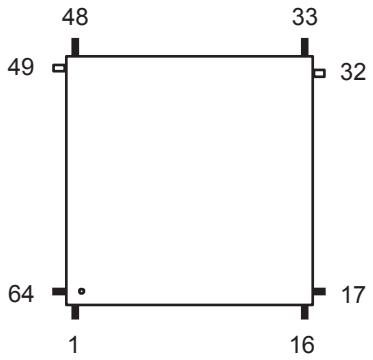


Figure 4-4. Orientation of the 64-lead LQFP Package



4.3.1 48-Lead LQFP and QFN Pinout

Table 4-4. 48-pin SAM3N4/2/1/0/00A Pinout

1	ADVREF	13	VDDIO	25	*TDI/PB4*	37	*TDO/TRACESWO/ PB5*
2	GND	14	PA16/PGMD4	26	PA6/PGMNOE	38	JTAGSEL
3	*PB0/AD4*	15	PA15/PGMD3	27	PA5/PGMRDY	39	*TMS/SWDIO/PB6*
4	*PB1/AD5*	16	PA14/PGMD2	28	PA4/PGMNCMD	40	*TCK/SWCLK/PB7*
5	*PB2/AD6*	17	PA13/PGMD1	29	NRST	41	VDDCORE
6	*PB3/AD7*	18	VDDCORE	30	TST	42	*ERASE/PB12*
7	VDDIN	19	PA12/PGMD0	31	PA3	43	*PB10*
8	VDDOUT	20	PA11/PGMM3	32	PA2/PGMEN2	44	*PB11*
9	PA17/PGMD5/AD0	21	PA10/PGMM2	33	VDDIO	45	*XOUT/PB8*
10	PA18/PGMD6/AD1	22	PA9/PGMM1	34	GND	46	*XIN/P/PB9/GMCK*
11	PA19/PGMD7/AD2	23	PA8/XOUT32/PG MM0	35	PA1/PGMEN1	47	VDDIO
12	PA20/AD3	24	PA7/XIN32/PGMN VALID	36	PA0/PGMEN0	48	VDDPLL

Note: The bottom pad of the QFN package must be connected to ground.

- Supply Monitor alarm
- RTC alarm
- RTT alarm

5.5.2 Wait Mode

The purpose of the wait mode is to achieve very low power consumption while maintaining the whole device in a powered state for a startup time of less than 10 µs. Current Consumption in Wait mode is typically 15 µA (total current consumption) if the internal voltage regulator is used or 8 µA if an external regulator is used.

In this mode, the clocks of the core, peripherals and memories are stopped. However, the core, peripherals and memories power supplies are still powered. From this mode, a fast start up is available.

This mode is entered via Wait for Event (WFE) instructions with LPM = 1 (Low Power Mode bit in PMC_FSMR). The Cortex-M3 is able to handle external or internal events in order to wake up the core (WFE). By configuring the WUP0-15 external lines as fast startup wake-up pins (refer to Section 5.7 “Fast Start-Up”). RTC or RTT Alarm wake-up events can be used to wake up the CPU (exit from WFE).

Entering Wait Mode:

- Select the 4/8/12 MHz fast RC oscillator as Main Clock
- Set the LPM bit in the PMC Fast Startup Mode Register (PMC_FSMR)
- Execute the Wait-For-Event (WFE) instruction of the processor

Note: Internal Main clock resynchronization cycles are necessary between the writing of MOSCRCEN bit and the effective entry in Wait mode. Depending on the user application, Waiting for MOSCRCEN bit to be cleared is recommended to ensure that the core will not execute undesired instructions.

5.5.3 Sleep Mode

The purpose of sleep mode is to optimize power consumption of the device versus response time. In this mode, only the core clock is stopped. The peripheral clocks can be enabled. The current consumption in this mode is application dependent.

This mode is entered via Wait for Interrupt (WFI) or Wait for Event (WFE) instructions with LPM = 0 in PMC_FSMR.

The processor can be woke up from an interrupt if WFI instruction of the Cortex M3 is used, or from an event if the WFE instruction is used to enter this mode.

5.5.4 Low Power Mode Summary Table

The modes detailed above are the main low power modes. Each part can be set to on or off separately and wake up sources can be individually configured. Table 5-1 below shows a summary of the configurations of the low power modes.

Table 5-1. Low Power Mode Configuration Summary

Mode	SUPC, 32 kHz Oscillator RTC RTT Backup Registers, POR (Backup Region)	Regulator	Core Memory Peripherals	Mode Entry	Potential Wake Up Sources	Core at Wake Up	PIO State while in Low Power Mode	PIO State at Wake Up	Consumption (2) (3)	Wake Up Time(1)
Backup Mode	ON	OFF	OFF (Not powered)	WFE +SLEEPDEEP bit = 1	WUP0-15 pins BOD alarm RTC alarm RTT alarm	Reset	Previous state saved	PIOA & PIOB & PIOC Inputs with pull ups	3 µA typ(4)	< 0.1 ms
Wait Mode	ON	ON	Powered (Not clocked)	WFE +SLEEPDEEP bit = 0 +LPM bit = 1	Any Event from: Fast startup through WUP0-15 pins RTC alarm RTT alarm	Clocked back	Previous state saved	Unchanged	5 µA/15 µA (5)	< 10 µs
Sleep Mode	ON	ON	Powered(7) (Not clocked)	WFE or WFI +SLEEPDEEP bit = 0 +LPM bit = 0	Entry mode = WFI Interrupt Only; Entry mode = WFE Any Enabled Interrupt and/or Any Event from: Fast start-up through WUP0-15 pins RTC alarm RTT alarm	Clocked back	Previous state saved	Unchanged	(6)	(6)

Notes:
1. When considering wake-up time, the time required to start the PLL is not taken into account. Once started, the device works with the 4/8/12 MHz Fast RC oscillator. The user has to add the PLL start-up time if it is needed in the system. The wake-up time is defined as the time taken for wake up until the first instruction is fetched.
2. The external loads on PIOs are not taken into account in the calculation.
3. Supply Monitor current consumption is not included.
4. Total Current consumption.
5. 5 µA on VDDCORE, 15 µA for total current consumption (using internal voltage regulator), 8 µA for total current consumption (without using internal voltage regulator).
6. Depends on MCK frequency.
7. In this mode the core is supplied and not clocked but some peripherals can be clocked.

6.3 Test Pin

The TST pin is used for JTAG Boundary Scan Manufacturing Test or Fast Flash programming mode of the SAM3N series. The TST pin integrates a permanent pull-down resistor of about 15 kΩ to GND, so that it can be left unconnected for normal operations. To enter fast programming mode, see the Fast Flash Programming Interface (FFPI) section. For more on the manufacturing and test mode, refer to the “Debug and Test” section of the product datasheet.

6.4 NRST Pin

The NRST pin is bidirectional. It is handled by the on-chip reset controller and can be driven low to provide a reset signal to the external components or asserted low externally to reset the microcontroller. It will reset the Core and the peripherals except the Backup region (RTC, RTT and Supply Controller). There is no constraint on the length of the reset pulse and the reset controller can guarantee a minimum pulse length. The NRST pin integrates a permanent pull-up resistor to VDDIO of about 100 kΩ . By default, the NRST pin is configured as an input.

6.5 ERASE Pin

The ERASE pin is used to reinitialize the Flash content (and some of its NVM bits) to an erased state (all bits read as logic level 1). It integrates a pull-down resistor of about 100 kΩ to GND, so that it can be left unconnected for normal operations.

This pin is debounced by SCLK to improve the glitch tolerance. When the ERASE pin is tied high during less than 100 ms, it is not taken into account. The pin must be tied high during more than 220 ms to perform a Flash erase operation.

The ERASE pin is a system I/O pin and can be used as a standard I/O. At startup, the ERASE pin is not configured as a PIO pin. If the ERASE pin is used as a standard I/O, startup level of this pin must be low to prevent unwanted erasing. Please refer to Section 11.2 “Peripheral Signals Multiplexing on I/O Lines” on page 42. Also, if the ERASE pin is used as a standard I/O output, asserting the pin to low does not erase the Flash.

9.1.3.4 Flash Speed

The user needs to set the number of wait states depending on the frequency used.

For more details, refer to the AC Characteristics sub section in the product Electrical Characteristics Section.

9.1.3.5 Lock Regions

Several lock bits used to protect write and erase operations on lock regions. A lock region is composed of several consecutive pages, and each lock region has its associated lock bit.

Table 9-1. Lock bit number

Product	Number of lock bits	Lock region size
SAM3N4	16	16 kbytes (64 pages)
SAM3N2	8	16 kbytes (64 pages)
SAM3N1	4	16 kbytes (64 pages)

If a locked-region's erase or program command occurs, the command is aborted and the EEFC triggers an interrupt.

The lock bits are software programmable through the EEFC User Interface. The command "Set Lock Bit" enables the protection. The command "Clear Lock Bit" unlocks the lock region.

Asserting the ERASE pin clears the lock bits, thus unlocking the entire Flash.

9.1.3.6 Security Bit Feature

The SAM3N features a security bit, based on a specific General Purpose NVM bit (GPNVM bit 0). When the security is enabled, any access to the Flash, either through the ICE interface or through the Fast Flash Programming Interface, is forbidden. This ensures the confidentiality of the code programmed in the Flash.

This security bit can only be enabled, through the command "Set General Purpose NVM Bit 0" of the EEFC User Interface. Disabling the security bit can only be achieved by asserting the ERASE pin at 1, after a full Flash erase is performed. When the security bit is deactivated, all accesses to the Flash are permitted.

It is important to note that the assertion of the ERASE pin should always be longer than 200 ms.

As the ERASE pin integrates a permanent pull-down, it can be left unconnected during normal operation. However, it is safer to connect it directly to GND for the final application.

9.1.3.7 Calibration Bits

NVM bits are used to calibrate the brownout detector and the voltage regulator. These bits are factory configured and cannot be changed by the user. The ERASE pin has no effect on the calibration bits.

9.1.3.8 Unique Identifier

Each device integrates its own 128-bit unique identifier. These bits are factory configured and cannot be changed by the user. The ERASE pin has no effect on the unique identifier.

The reset circuitry is based on a zero-power power-on reset cell and a brownout detector cell. The zero-power power-on reset allows the Supply Controller to start properly, while the software-programmable brownout detector allows detection of either a battery discharge or main voltage loss.

The Slow Clock generator is based on a 32 kHz crystal oscillator and an embedded 32 kHz RC oscillator. The Slow Clock defaults to the RC oscillator, but the software can enable the crystal oscillator and select it as the Slow Clock source.

The Supply Controller starts up the device by sequentially enabling the internal power switches and the Voltage Regulator, then it generates the proper reset signals to the core power supply.

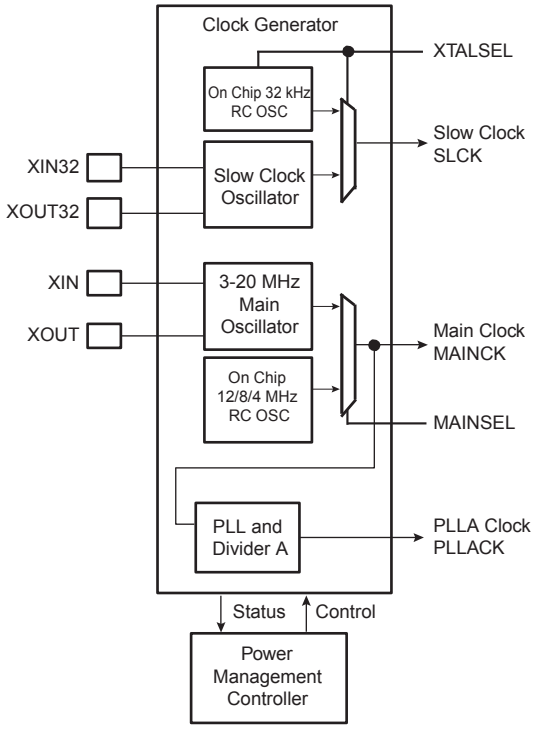
It also enables to set the system in different low power modes and to wake it up from a wide range of events.

10.5 Clock Generator

The Clock Generator is made up of:

- One Low Power 32768Hz Slow Clock Oscillator with bypass mode
- One Low-Power RC Oscillator
- One 3-20 MHz Crystal or Ceramic resonator Oscillator, which can be bypassed
- One Fast RC Oscillator factory programmed, 3 output frequencies can be selected: 4, 8 or 12 MHz. By default 4 MHz is selected.
- One 60 to 130 MHz programmable PLL, capable to provide the clock MCK to the processor and to the peripherals. The input frequency of PLL is from 3.5 to 20 MHz.

Figure 10-2. Clock Generator Block Diagram



11.2.1 PIO Controller A Multiplexing

Table 11-2. Multiplexing on PIO Controller A (PIOA)

I/O Line	Peripheral A	Peripheral B	Peripheral C	Extra Function	System Function	Comments
PA0	PWM0	TIOA0		WKUP0		High drive
PA1	PWM1	TIOB0		WKUP1		High drive
PA2	PWM2	SCK0	DATRG	WKUP2		High drive
PA3	TWD0	NPCS3				High drive
PA4	TWCK0	TCLK0		WKUP3		
PA5	RXD0	NPCS3		WKUP4		
PA6	TXD0	PCK0				
PA7	RTS0	PWM3			XIN32	
PA8	CTS0	ADTRG		WKUP5	XOUT32	
PA9	URXD0	NPCS1		WKUP6		
PA10	UTXD0	NPCS2				
PA11	NPCS0	PWM0		WKUP7		
PA12	MISO	PWM1				
PA13	MOSI	PWM2				
PA14	SPCK	PWM3		WKUP8		
PA15		TIOA1		WKUP14		
PA16		TIOB1		WKUP15		
PA17		PCK1		AD0		
PA18		PCK2		AD1		
PA19				AD2/WKUP9		
PA20				AD3/WKUP10		
PA21	RXD1	PCK1		AD8		64/100-pin versions
PA22	TXD1	NPCS3		AD9		64/100-pin versions
PA23	SCK1	PWM0				64/100-pin versions
PA24	RTS1	PWM1				64/100-pin versions
PA25	CTS1	PWM2				64/100-pin versions
PA26		TIOA2				64/100-pin versions
PA27		TIOB2				64/100-pin versions
PA28		TCLK1				64/100-pin versions
PA29		TCLK2				64/100-pin versions
PA30		NPCS2		WKUP11		64/100-pin versions
PA31	NPCS1	PCK2				64/100-pin versions

11.2.3 PIO Controller C Multiplexing

I/O Line	Peripheral A	Peripheral B	Peripheral C	Extra Function	System Function	Comments
PC0						100-pin version
PC1						100-pin version
PC2						100-pin version
PC3						100-pin version
PC4		NPCS1				100-pin version
PC5						100-pin version
PC6						100-pin version
PC7		NPCS2				100-pin version
PC8		PWM0				100-pin version
PC9		PWM1				100-pin version
PC10		PWM2				100-pin version
PC11		PWM3				100-pin version
PC12				AD12		100-pin version
PC13				AD10		100-pin version
PC14		PCK2				100-pin version
PC15				AD11		100-pin version
PC16		PCK0				100-pin version
PC17		PCK1				100-pin version
PC18		PWM0				100-pin version
PC19		PWM1				100-pin version
PC20		PWM2				100-pin version
PC21		PWM3				100-pin version
PC22		PWM0				100-pin version
PC23		TIOA3				100-pin version
PC24		TIOB3				100-pin version
PC25		TCLK3				100-pin version
PC26		TIOA4				100-pin version
PC27		TIOB4				100-pin version
PC28		TCLK4				100-pin version
PC29		TIOA5		AD13		100-pin version
PC30		TIOB5		AD14		100-pin version
PC31		TCLK5		AD15		100-pin version

  - Support for two PDC channels with connection to receiver and transmitter (for UART0 only)

12.4 USART

- Programmable Baud Rate Generator
- 5- to 9-bit full-duplex synchronous or asynchronous serial communications
  - 1, 1.5 or 2 stop bits in Asynchronous Mode or 1 or 2 stop bits in Synchronous Mode
  - Parity generation and error detection
  - Framing error detection, overrun error detection
  - MSB- or LSB-first
  - Optional break generation and detection
  - By 8 or by-16 over-sampling receiver frequency
  - Hardware handshaking RTS-CTS
  - Receiver time-out and transmitter timeguard
  - Optional Multi-drop Mode with address generation and detection
- RS485 with driver control signal
- ISO7816, T = 0 or T = 1 Protocols for interfacing with smart cards (Only on USART0)
  - NACK handling, error counter with repetition and iteration limit
- SPI Mode
  - Master or Slave
  - Serial Clock programmable Phase and Polarity
  - SPI Serial Clock (SCK) Frequency up to MCK/4
- IrDA modulation and demodulation (Only on USART0)
  - Communication at up to 115.2 Kbps
- Test Modes
  - Remote Loopback, Local Loopback, Automatic Echo
- PDC support (for USART0 only)

12.5 Timer Counter (TC)

- Six 16-bit Timer Counter Channels
- Wide range of functions including:
  - Frequency Measurement
  - Event Counting
  - Interval Measurement
  - Pulse Generation
  - Delay Timing
  - Pulse Width Modulation
  - Up/down Capabilities
- Each channel is user-configurable and contains:
  - Three external clock inputs
  - Five internal clock inputs

Figure 13-3. 64and4B·leadLQFP Package Drawing

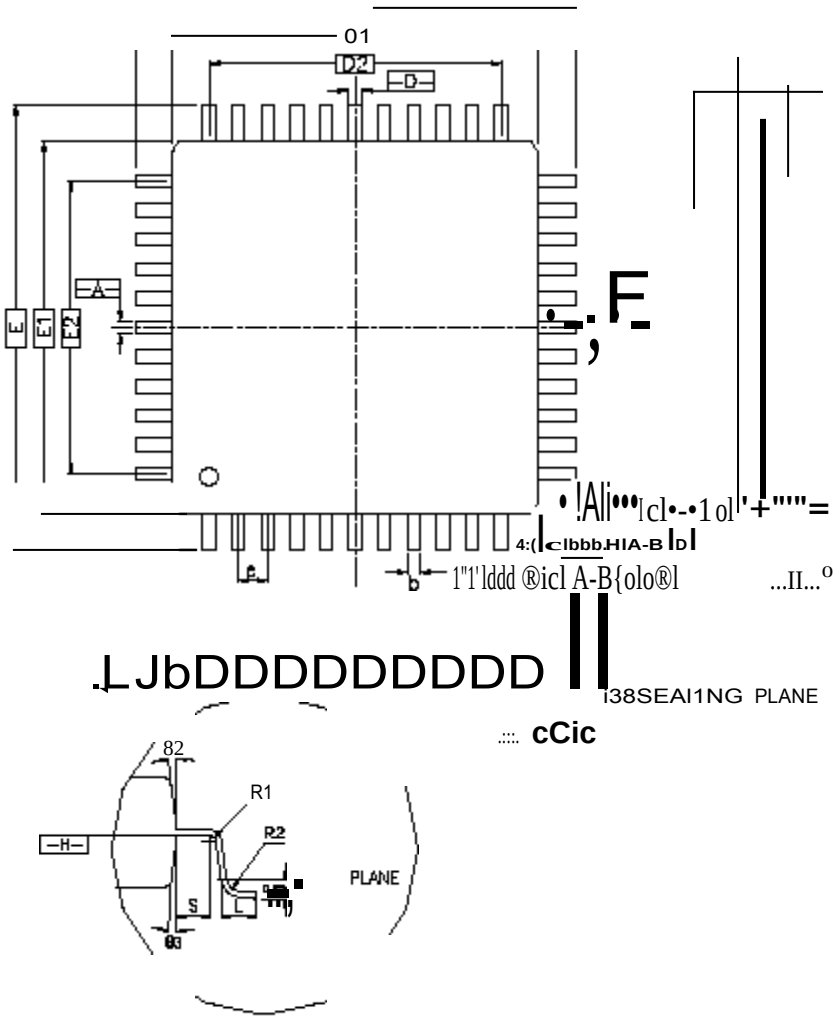
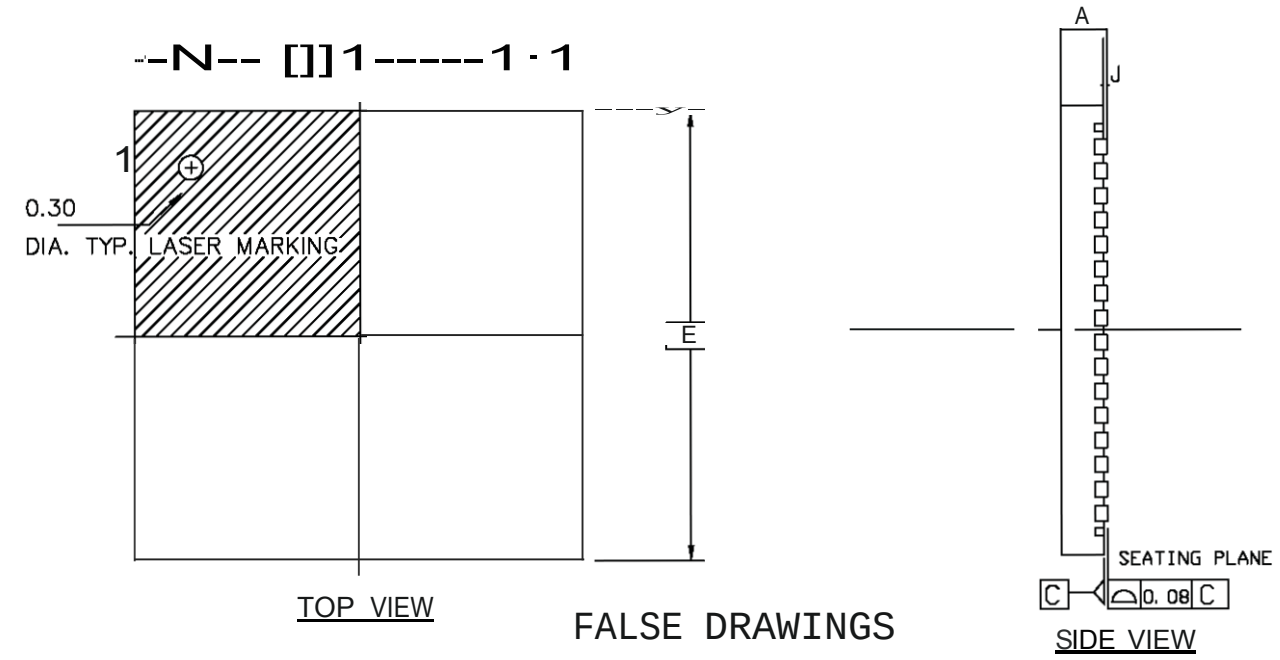


Table 13-2. 64-lead LQFP Package Dimensions (in mm)

Symbol	Millimeter			Inch		
	Min	**Nom**	**Max**	**Min**	**Nom**	**Max**
A	–	–	1.60	–	–	0.063
A1	0.05	–	0.15	0.002	–	0.006
A2	1.35	1.40	1.45	0.053	0.055	0.057
D	12.00 BSC			0.472 BSC		
D1	10.00 BSC			0.383 BSC		
E	12.00 BSC			0.472 BSC		
E1	10.00 BSC			0.383 BSC		
R2	0.08	–	0.20	0.003	–	0.008
R1	0.08	–	–	0.003	–	–
q	0°	3.5°	7°	0°	3.5°	7°
θ_1	0°	–	–	0°	–	–
θ_2	11°	12°	13°	11°	12°	13°
θ_3	11°	12°	13°	11°	12°	13°
c	0.09	–	0.20	0.004	–	0.008
L	0.45	0.60	0.75	0.018	0.024	0.030
L1	1.00 REF			0.039 REF		
S	0.20	–	–	0.008	–	–
b	0.17	0.20	0.27	0.007	0.008	0.011
e	0.50 BSC.			0.020 BSC.		
D2	7.50			0.285		
E2	7.50			0.285		
Tolerances of Form and Position						
aaa	0.20			0.008		
bbb	0.20			0.008		
ccc	0.08			0.003		
ddd	0.08			0.003		

Figure 13-4. 48-pad QFN Package Drawing



COMMON DIMENSIONS IN MM

SYMBOL	MIN.	NOM.	MAX.	NOTES
A	0.80	0.85	0.90	
J	0.00	----	0.05	
D/E		7.00 BSC		
D2/E2	5.00	5.10	5.20	
N		48		
e		0.50 BSC		
L	0.30	0.40	0.50	
b	0.18	0.25	0.30	

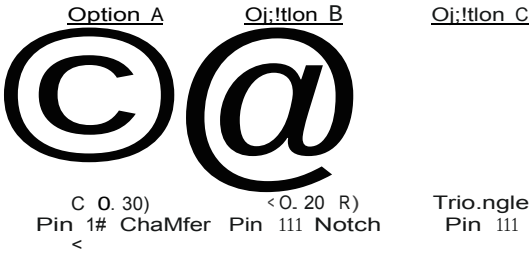
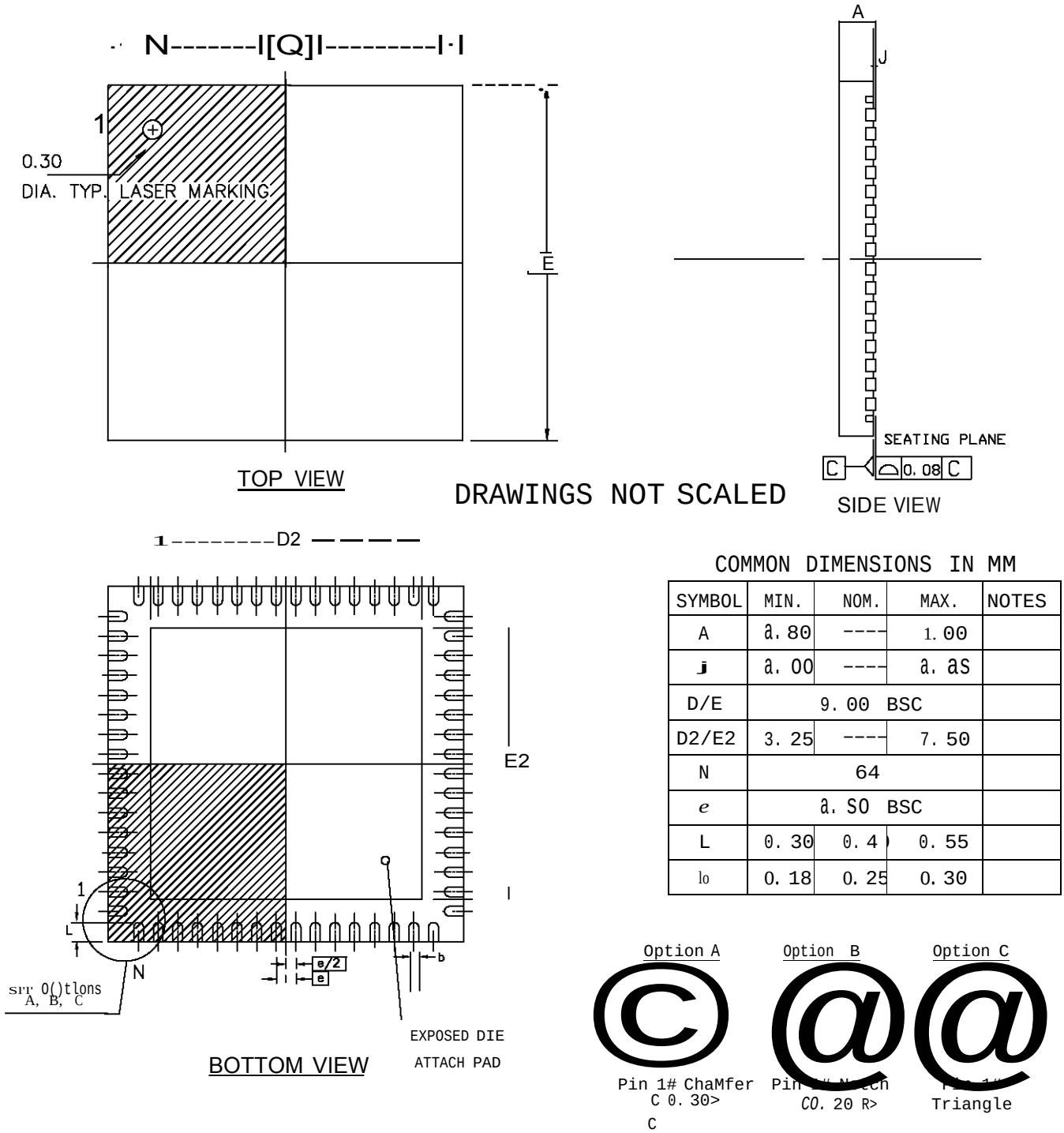


Figure 13-5. 64-pad QFN Package Drawing



COMMON DIMENSIONS IN MM

SYMBOL	MIN.	NOM.	MAX.	NOTES
A	0.80	----	1.00	
j	0.00	----	0.05	
D/E		9.00 BSC		
D2/E2	3.25	----	7.50	
N		64		
e		0.50 BSC		
L	0.30	0.40	0.55	
lo	0.18	0.25	0.30	

Table 14-1.

Ordering Code	MRL	Flash (Kbytes)	Package	Package Type	Temperature Operating Range
ATSAM3N1AA-AU	A	64	LQFP48	Green	Industrial -40°C to 85°C
ATSAM3N1AB-AU	B	64	LQFP48	Green	Industrial -40°C to 85°C
ATSAM3N1AA-MU	A	64	QFN48	Green	Industrial -40°C to 85°C
ATSAM3N1AB-MU	B	64	QFN48	Green	Industrial -40°C to 85°C
ATSAM3N0CA-AU	A	32	LQFP100	Green	Industrial -40°C to 85°C
ATSAM3N0CA-CU	A	32	TFBGA100	Green	Industrial -40°C to 85°C
ATSAM3N0BA-AU	A	32	LQFP64	Green	Industrial -40°C to 85°C
ATSAM3N0BA-MU	A	32	QFN64	Green	Industrial -40°C to 85°C
ATSAM3N0AA-AU	A	32	LQFP48	Green	Industrial -40°C to 85°C
ATSAM3N0AA-MU	A	32	QFN48	Green	Industrial -40°C to 85°C
ATSAM3N00BA-AU	A	16	LQFP64	Green	Industrial -40°C to 85°C
ATSAM3N00BA-MU	A	16	QFN64	Green	Industrial -40°C to 85°C
ATSAM3N00AA-AU	A	16	LQFP48	Green	Industrial -40°C to 85°C
ATSAM3N00AA-MU	A	16	QFN48	Green	Industrial -40°C to 85°C

Revision History

Doc. Rev. 11011BS	Comments	Change Request Ref.
	Overview:	
	All mentions of 100-ball LFBGA changed into 100-ball TFBGA	8044
	Section 8. “Product Mapping”, Heading was ‘Memories’. Changed to ‘Product Mapping’	7685
	Section 4.1.4 “100-ball TFBGA Pinout”, whole pinout table updated	7201
	Updated package dimensions in ‘Features’	7965

Doc. Rev	Comments	Change Request Ref.
11011AS	First issue	